

SOT2167-2

LFBGA306, low profile fine-pitched ball grid array package,
306 terminals, 0.5 mm pitch, 11 mm x 11 mm x 1.124 mm body

22 April 2022

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA306
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	03-10-2022
Manufacturer package code	98ASA01880D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	11	-	mm
package width	-	11	-	mm
seated height	-	1.124	1.22	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	306	-	



LFBGA306, low profile fine-pitched ball grid array package, 306 terminals, 0.5 mm pitch, 11 mm x 11 mm x 1.124 mm body

2 Package outline

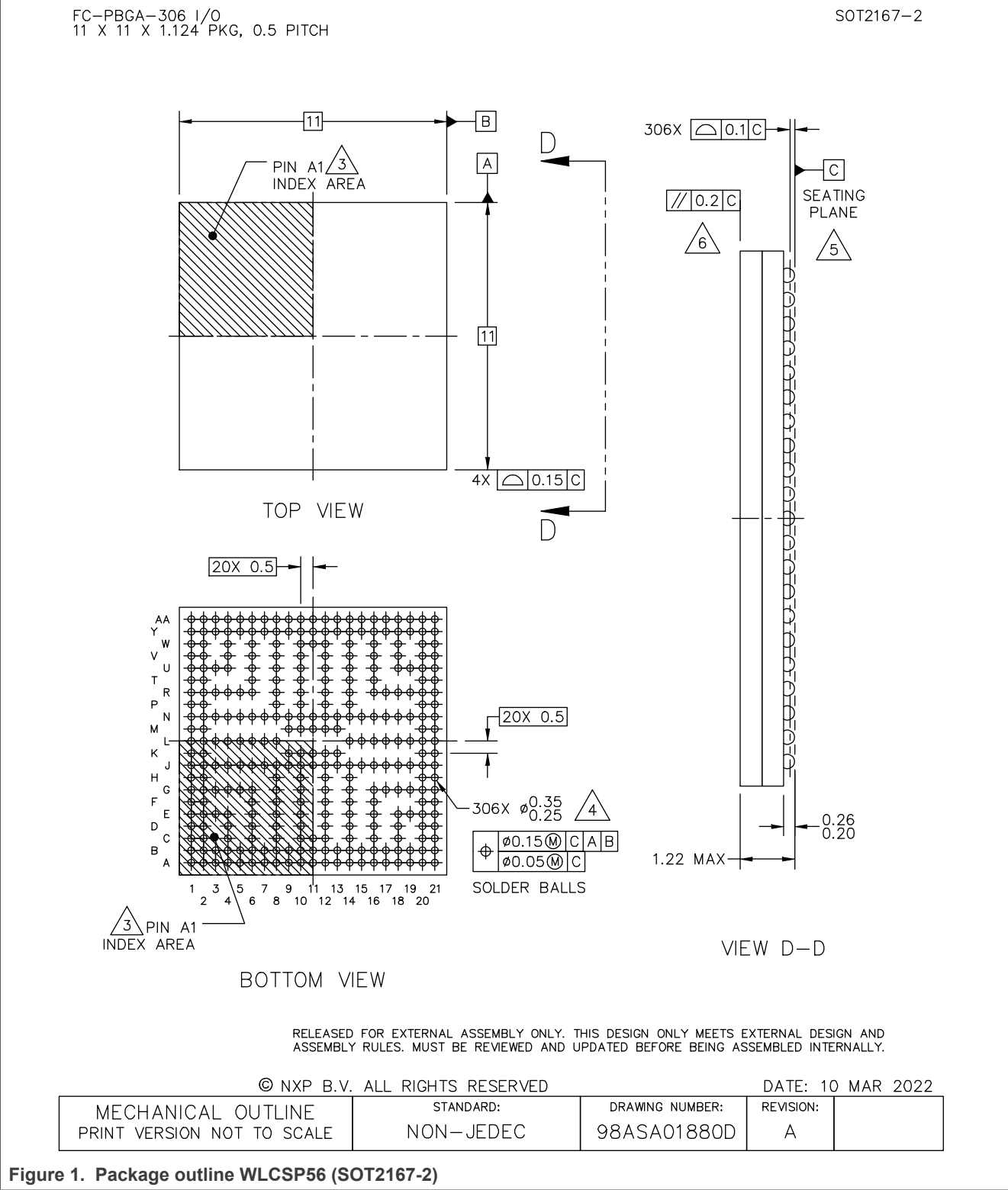
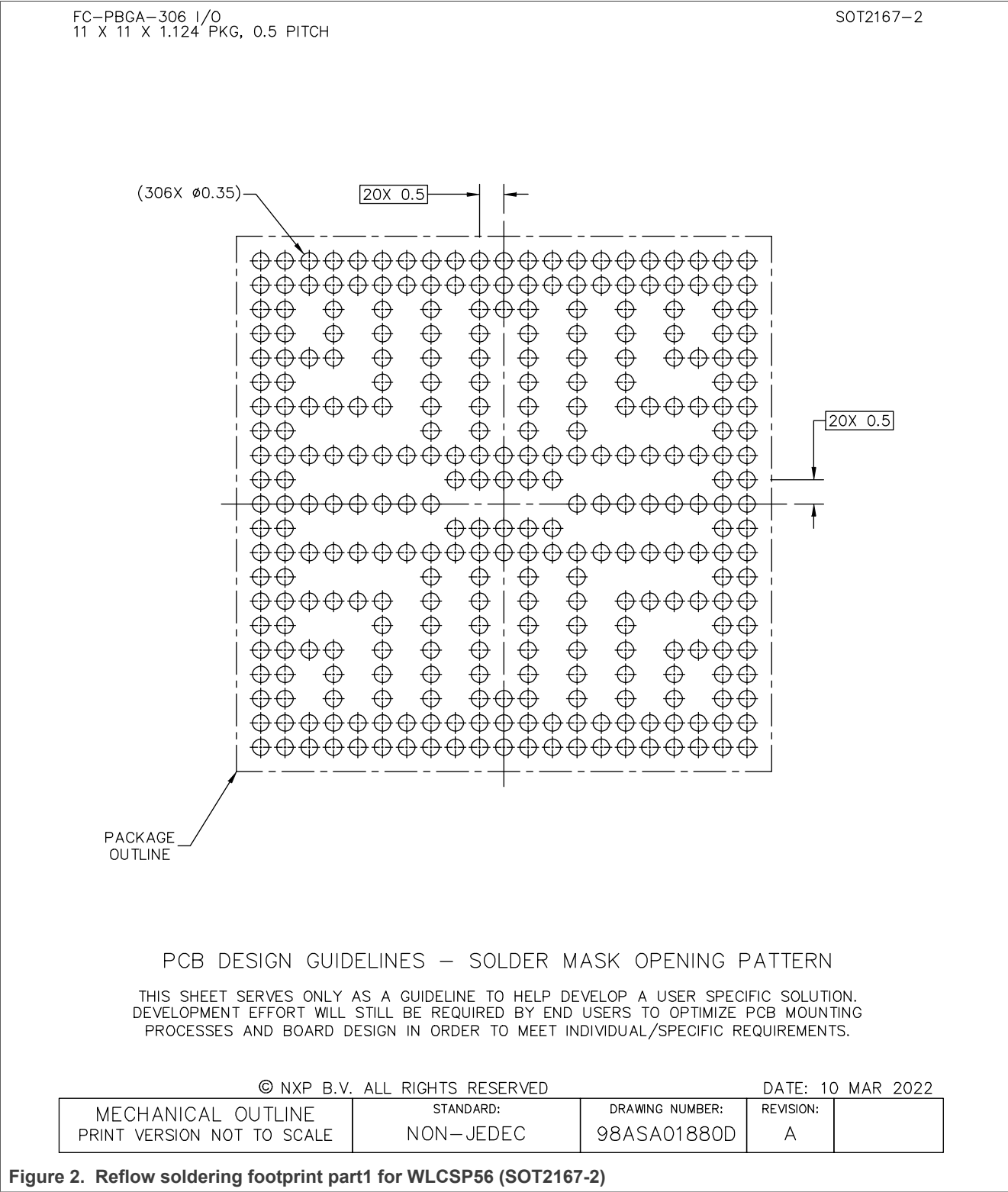


Figure 1. Package outline WLCSP56 (SOT2167-2)

LFBGA306, low profile fine-pitched ball grid array package, 306 terminals, 0.5 mm pitch, 11 mm x 11 mm x 1.124 mm body

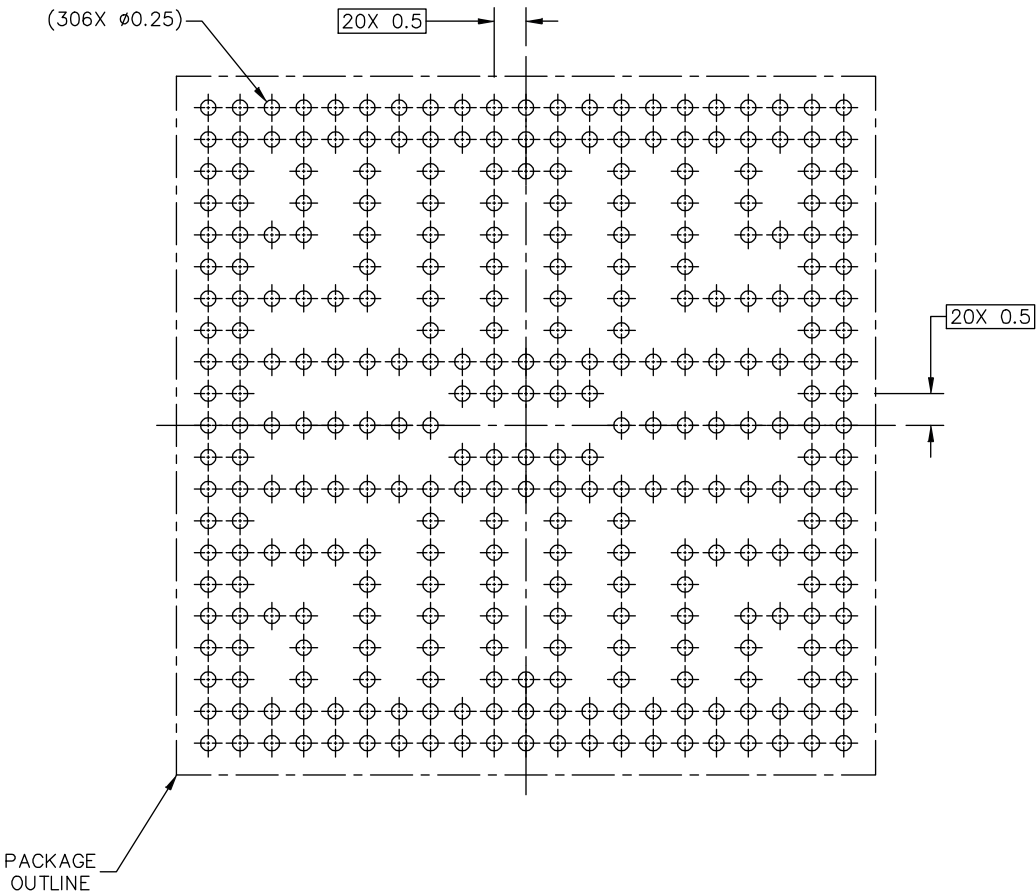
3 Soldering



LFBGA306, low profile fine-pitched ball grid array package, 306 terminals, 0.5 mm pitch, 11 mm x 11 mm
x 1.124 mm body

FC-PBGA-306 I/O
11 X 11 X 1.124 PKG, 0.5 PITCH

SOT2167-2



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION.
DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING
PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

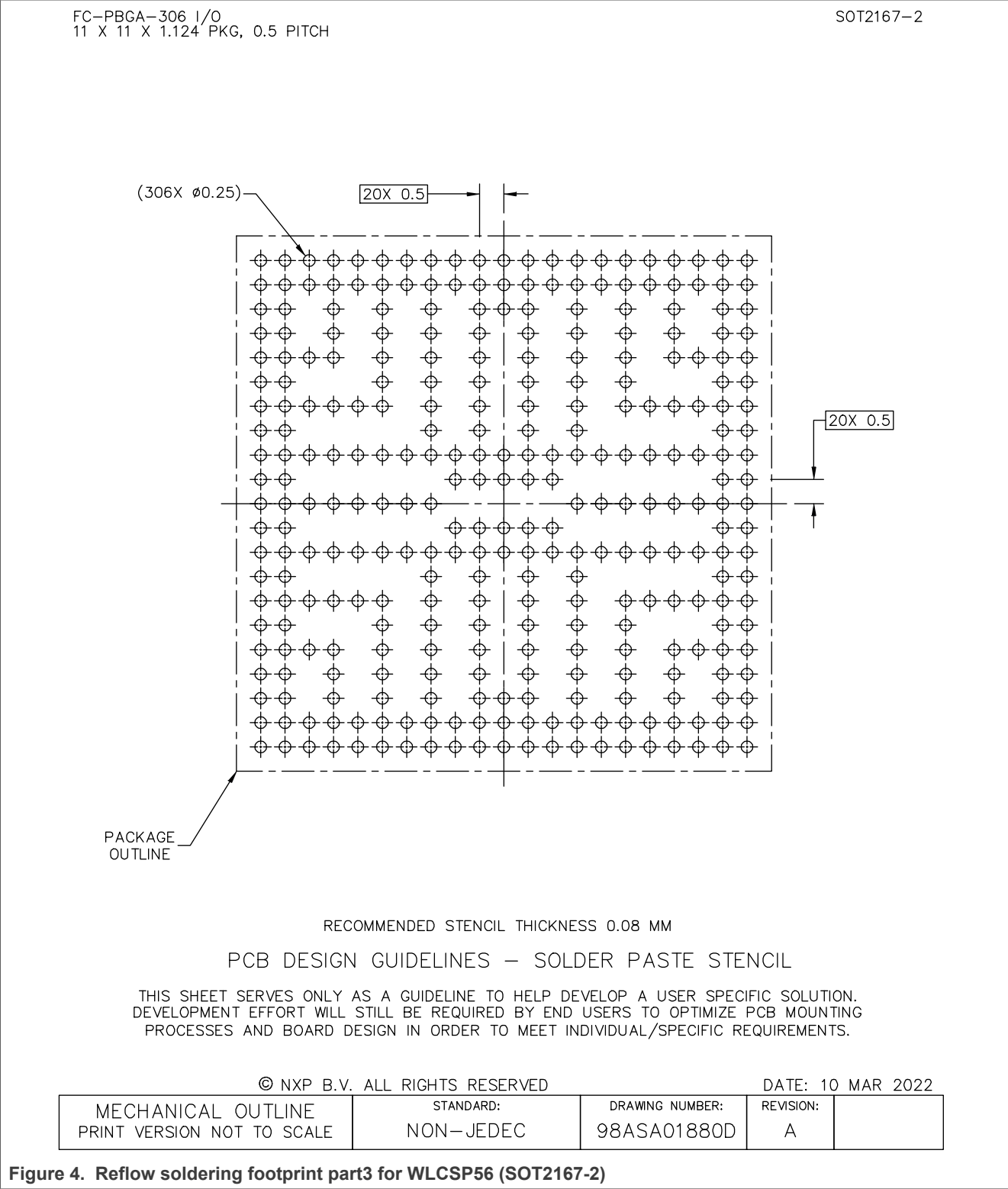
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DATE: 10 MAR 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01880D	REVISION: A	
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Figure 3. Reflow soldering footprint part2 for WLCSP56 (SOT2167-2)

LFBGA306, low profile fine-pitched ball grid array package, 306 terminals, 0.5 mm pitch, 11 mm x 11 mm x 1.124 mm body



LFBGA306, low profile fine-pitched ball grid array package, 306 terminals, 0.5 mm pitch, 11 mm x 11 mm
x 1.124 mm body

FC-PBGA-306 I/O
11 X 11 X 1.124 PKG, 0.5 PITCH

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NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 5. Package outline note WLCSP56 (SOT2167-2)

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Contents

1	Package summary	1
2	Package outline	2
3	Soldering	3
4	Legal information	7